



US00D865689S

(12) **United States Design Patent**
Wang et al.

(10) **Patent No.:** **US D865,689 S**
(45) **Date of Patent:** **** Nov. 5, 2019**

(54) **ELECTRICAL MODULE**

H05K 7/1435; H05K 5/00; H05K 1/14;
H01L 23/24; H01L 23/36; H01L 23/48

See application file for complete search history.

(71) Applicants: **Microduino Inc.**, Westlake Village, CA
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(US)

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(73) Assignee: **MICRODUINO INC.**, Beijing (CN)

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(**) Term: **15 Years**

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(21) Appl. No.: **29/624,178**

Primary Examiner — Angela J Lee
Assistant Examiner — Shawn T Gingrich
(74) *Attorney, Agent, or Firm* — Anova Law Group,
PLLC

(22) Filed: **Oct. 30, 2017**

Related U.S. Application Data

(60) Division of application No. 29/536,822, filed on Aug.
19, 2015, now abandoned, which is a
continuation-in-part of application No. 14/721,341,
filed on May 26, 2015, now Pat. No. 9,801,300.

(57) **CLAIM**

The ornamental design for electrical module, as shown and
described.

DESCRIPTION

(30) **Foreign Application Priority Data**

Feb. 20, 2015 (CN) 2015 1 0085854

(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/110, 118, 123, 133, 145–147, 149,
D13/154, 173, 182, 184, 199; D14/240,
D14/435–438
CPC H05K 7/00; H05K 7/14; H05K 7/1427;

FIG. 1 is a top perspective view of an electrical module in
accordance with the present invention;
FIG. 2 is a bottom perspective view of the electrical module
shown in FIG. 1;
FIG. 3 is a top view of the electrical module shown in FIG.
1;
FIG. 4 is a bottom view of the electrical module shown in
FIG. 1;
FIG. 5 is a left side view of the electrical module shown in
FIG. 1;
FIG. 6 is a right side view of the electrical module shown in
FIG. 1;

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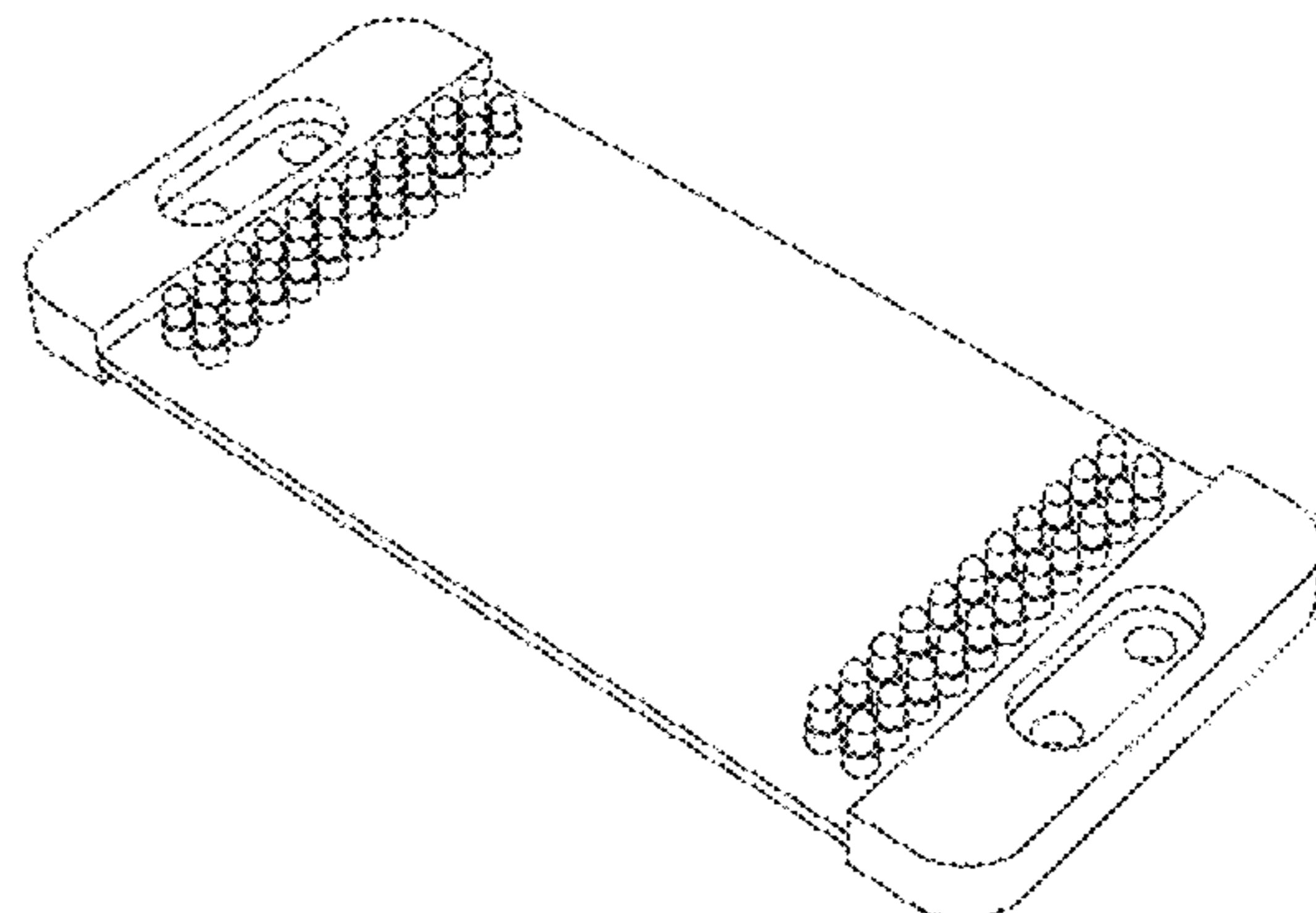
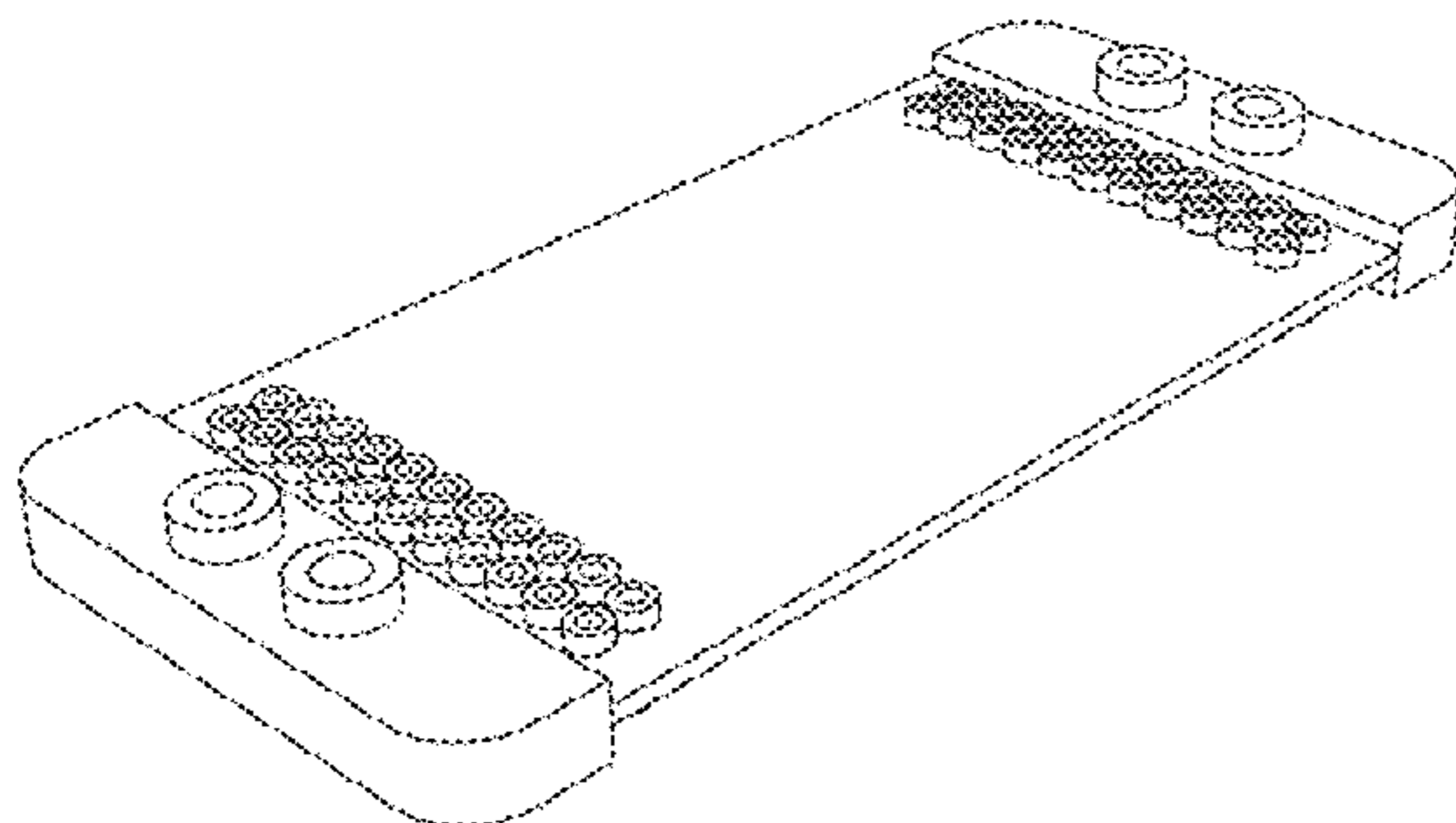


FIG. 7 is a front view of the electrical module shown in FIG. 1; and, FIG. 8 is a back view of the electrical module shown in FIG. 1.

1 Claim, 4 Drawing Sheets

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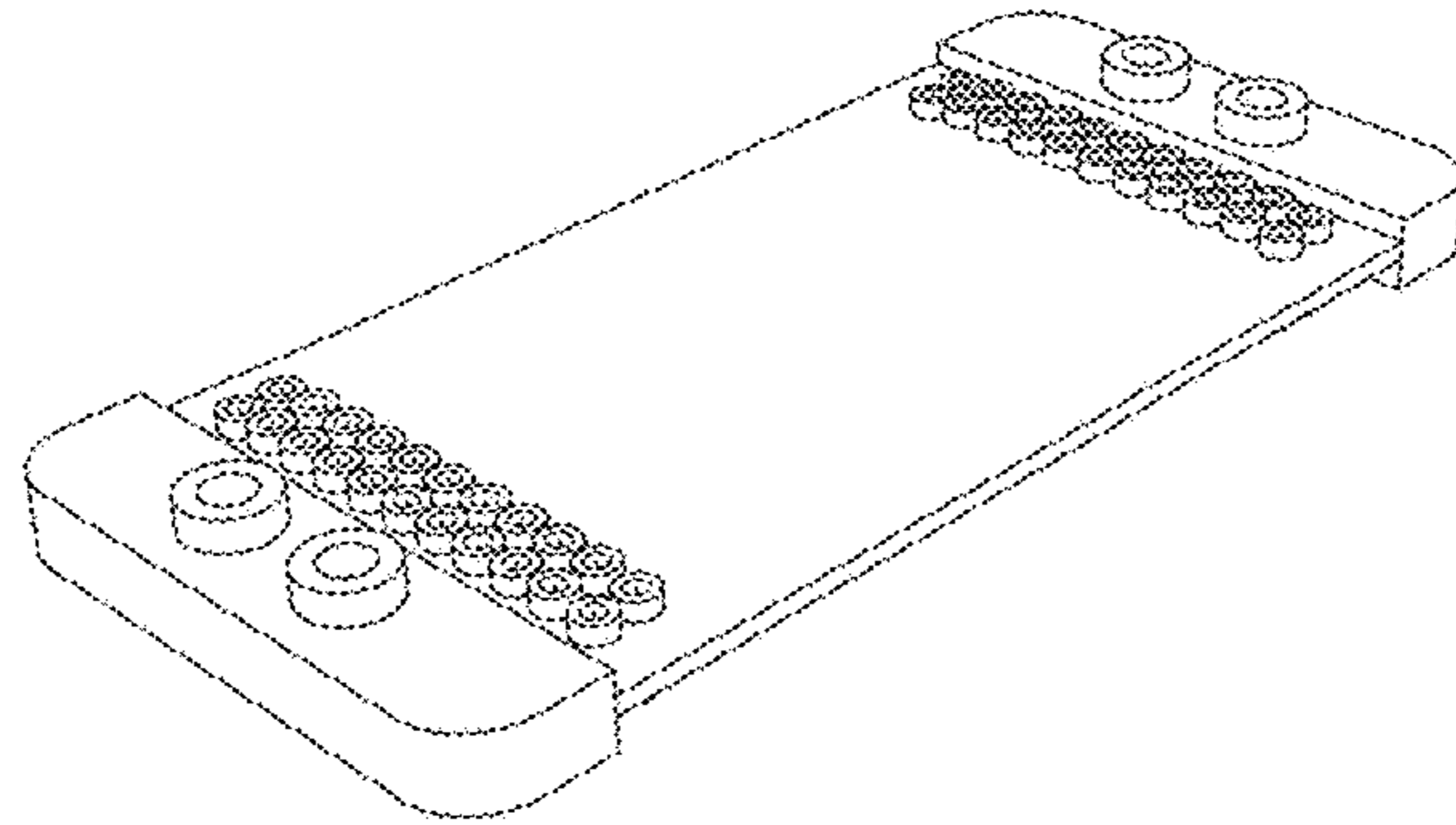


FIG. 1

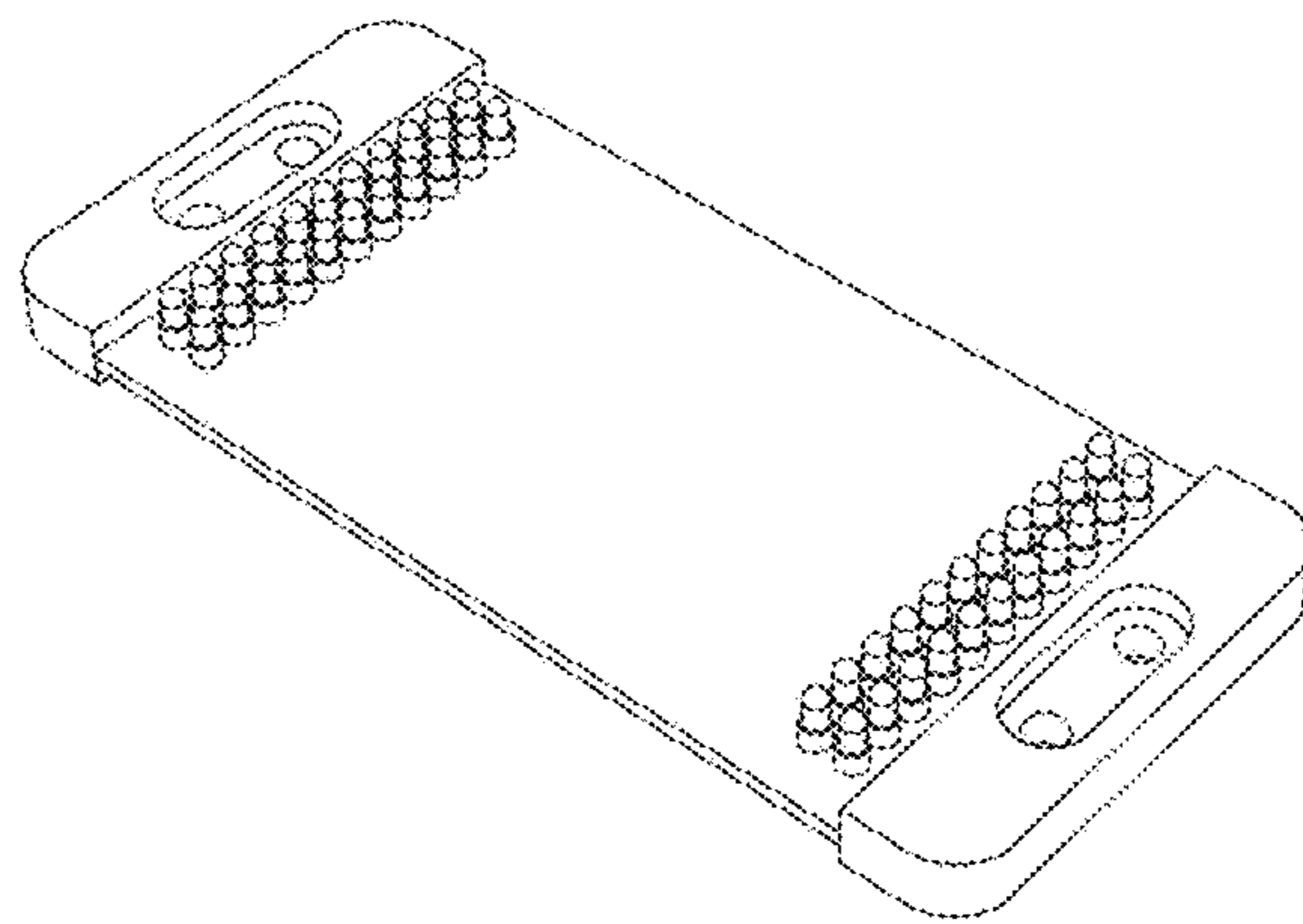


FIG. 2



FIG. 3



FIG. 4

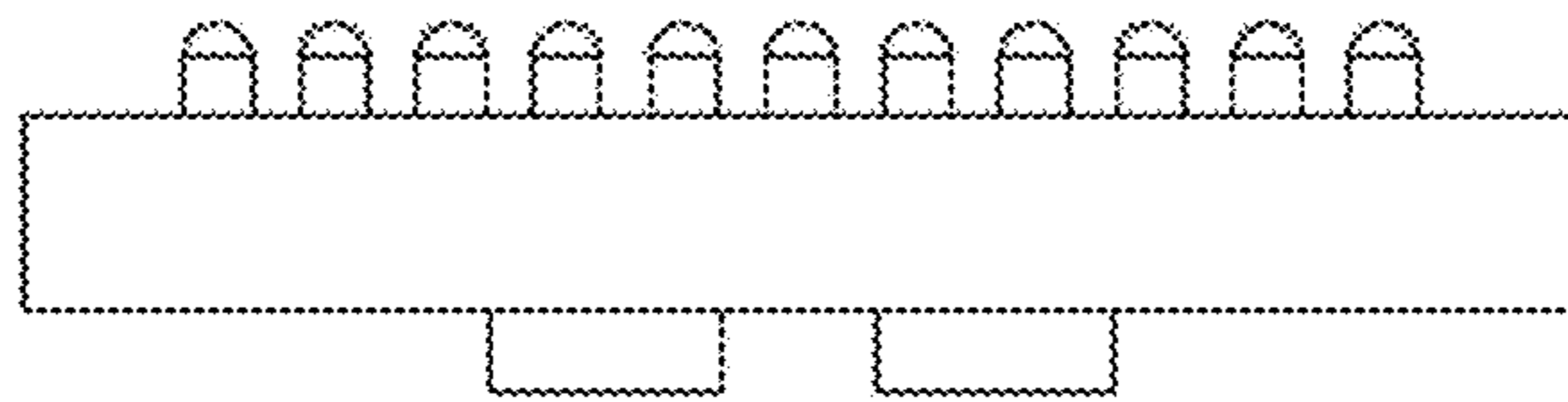


FIG. 5

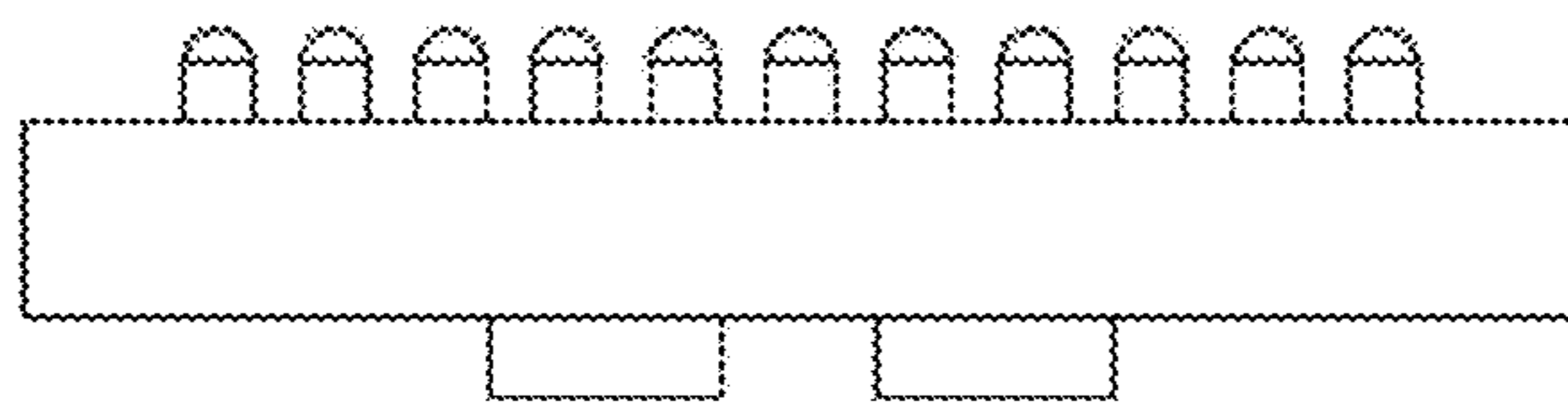


FIG. 6

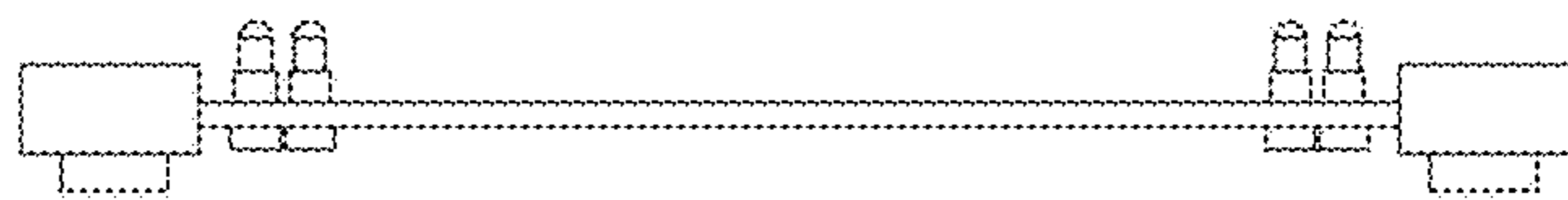


FIG. 7

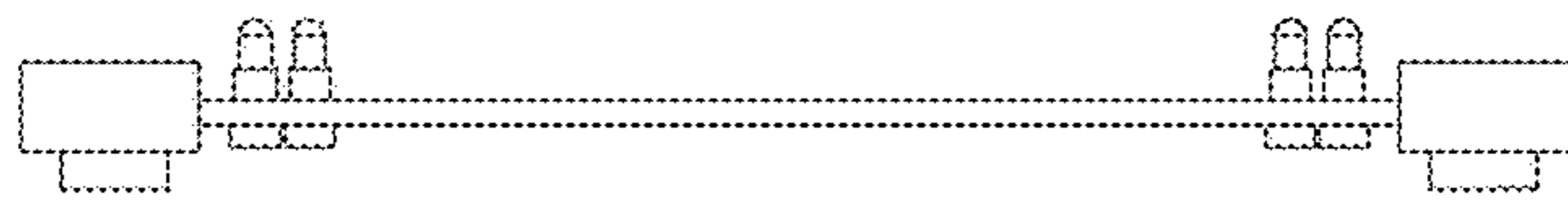


FIG. 8

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : D865,689 S
APPLICATION NO. : 29/624178
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Page 1 of 1

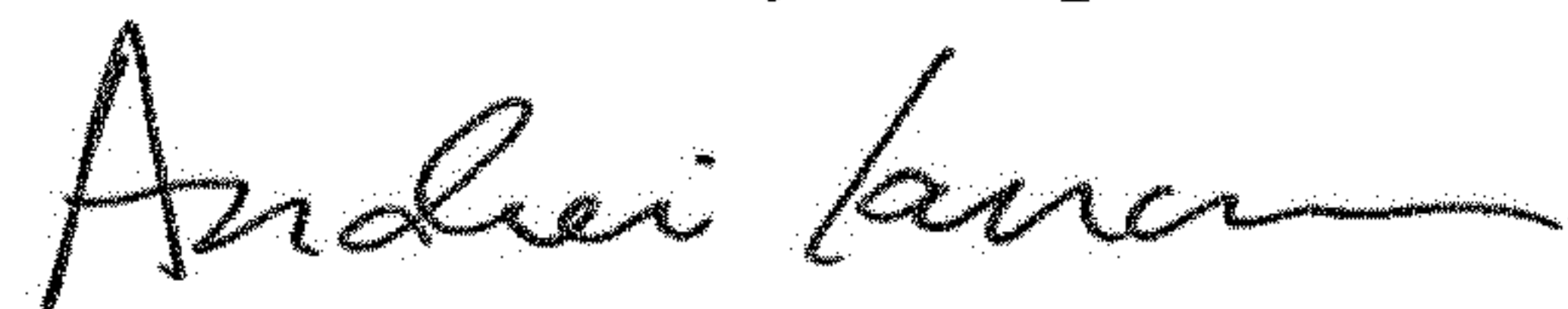
It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the Title Page

Item (73), should read:

(73) Assignees: Microduino Inc., Westlake Village, CA, (US);
Meike Technology (Beijing) Ltd., Beijing, (CN)

Signed and Sealed this
Fourteenth Day of April, 2020



Andrei Iancu
Director of the United States Patent and Trademark Office